Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
custreq@latticesemi.com

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Package: 484 fpBGA
Total Device Weight 3.141 Grams

Package Code: BFG484
Products: LFCPNX-100

Assembly: ASEK
Size (mm): 19 x 19
Lead pitch (mm): 1.0
MSL: 3
Reflow max (ºC): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	0.89%	0.0280						Die size: 8.22 x 7.19 mm
			0.89%	0.0280	Silicon chip	7440-21-3	100.00%	
Mold Compound	73.72%	2.3158						Mold Compound: CEL-9750ZHF10AKL-U (ULA)
			3.69%	0.1158	Epoxy Resin	-	5.00%	
			3.69%	0.1158	Phenol Resin	-	5.00%	
			0.15%	0.0046	Carbon Black	1333-86-4	0.20%	
			64.73%	2.0333	Silica	60676-86-0	87.80%	
			1.47%	0.0463	Others	-	2.00%	
D/A Epoxy	0.32%	0.0100						Die attach: Henkel (Ablebond) 2100A
			0.25%	0.0080	Silver	7440-22-4	80.00%	
			0.06%	0.0020	Esters & resins	-	20.00%	
Wire	0.19%	0.0061						0.8 mil diameter; 1 wire per solder ball
			0.19%	0.0059	Copper	7440-50-8	96.55%	
			0.01%	0.0002	Palladium	7440-05-3	3.10%	
			0.00%	0.0000	Gold	7440-57-5	0.35%	
Solder Balls	10.21%	0.3207						SAC305
			9.85%	0.3095	Tin (Sn)	7440-31-5	96.50%	
			0.31%	0.0096	Silver (Ag)	7440-22-4	3.00%	
			0.05%	0.0016	Copper (Cu)	7440-50-8	0.50%	
Substrate	4.69%	0.1475						MGC CCL-HL832NX-A
			1.50%	0.0472	BT Resins	-	32.00%	
			3.19%	0.1003	Glass fiber	65997-17-3	68.00%	
Foil	7.92%	0.2489						
			7.91%	0.2486	Copper	7440-50-8	99.90%	
			0.01%	0.0002	OSP	-	0.10%	
Solder Mask	2.05%	0.0645						Taiyo Ink PSR4000 AUS 308
			1.15%	0.0363	Quartz	14808-60-7	56.20%	
			0.33%	0.0103	3-methoxy-3-methylbutylacetate	103429-90-9	16.00%	
			0.45%	0.0142	Barium Sulfate	7727-43-7	22.00%	
			0.06%	0.0019	Talc (containing no asbestiform fibers)	14807-96-6	3.00%	
			0.06%	0.0018	Trade secret ingredients	-	2.80%	

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